

TOSHIBA (DISCRETE/OPTO)

39 DE 9097250 0002242 9

1S2711 1500V 1.5A

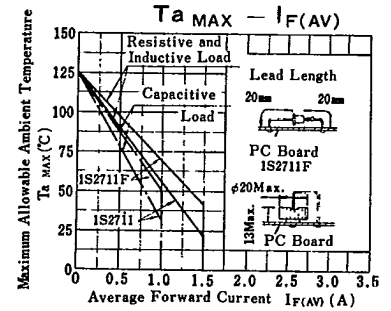
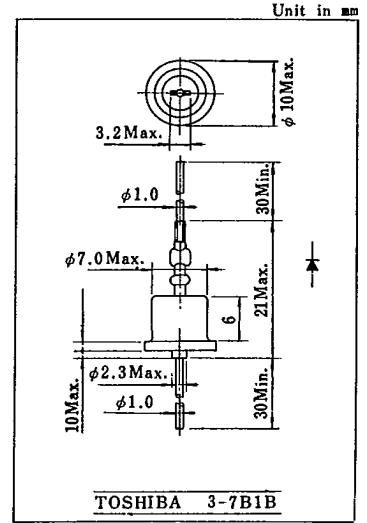
MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V _{RRM}	1500	V
Non-Repetitive Peak Reverse Voltage	V _{RSM}	1600	V
Average Forward Current (T _a =20°C)	I _{F(AV)}	1.5	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	I _{FSM}	60(50Hz)	A
Junction Temperature	T _j	-40~125	°C
Storage Temperature Range	T _{stg}	-40~150	°C

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	V _{FM}	I _{FM} =2.0A, T _j =25°C	-	-	1.2	V
Repetitive Peak Reverse Current	I _{RRM} (1)	V _{RRM} =Rated, T _j =25°C	-	-	10	μA
	I _{RRM} (2)	V _{RRM} =Rated, T _j =125°C	-	-	600	
Reverse Recovery Time	t _{rr}	I _F =20mA, I _R =1mA, T _j =25°C	-	-	20	μs
Forward Recovery Voltage	V _{fr}	I _F =0.1A, t _r =100ns, t _p =5μs, T _j =25°C	-	-	5	V

- Notes : 1. Soldering : 5mm is the minimum to be kept between case and soldering part.
 2. Lead Bending : 5mm is the minimum to be kept from the case when bend the lead wire.



3JH61 600V 3A

MAXIMUM RATINGS

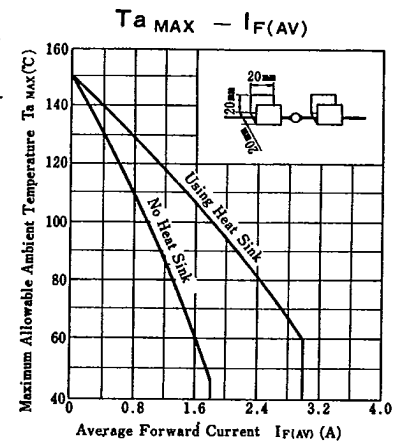
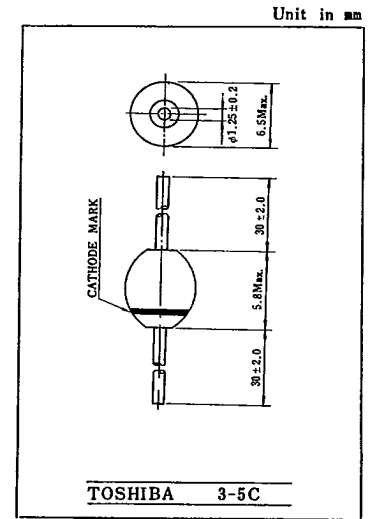
CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	3BH61	100	V
	3DH61	200	
	3GH61	400	
	3JH61	600	
Average Forward Current	I _{F(AV)}	1.5 * 1 3.0 * 2	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	I _{FSM}	60(50Hz)	A
Junction Temperature	T _j	-40~150	°C
Storage Temperature Range	T _{stg}	-40~150	°C

- * 1 No Heat Sink * 2 With Heat Sink

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	V _{FM}	I _{FM} =3A, T _j =25°C	-	-	1.4	V
Repetitive Peak Reverse Current	I _{RRM} (1)	V _{RRM} = Rated, T _j =25°C	-	-	20	μA
	I _{RRM} (2)	V _{RRM} = Rated, T _j =150°C	-	-	3000	
Reverse Recovery Time	t _{rr} (1)	I _F =20mA, I _R =1mA, T _j =25°C	-	-	1.5	μs
	t _{rr} (2)	I _F =20mA, I _R =20mA, T _j =25°C	-	-	0.5	
Forward Recovery Voltage	V _{fr}	I _F =0.1A, t _p =5μs, T _j =25°C	-	-	10	V

- Notes : 1. Soldering : 5mm is the minimum to be kept between case and soldering part.
 2. Lead Bending : 5mm is the minimum to be kept from the case when bend the lead wire.



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